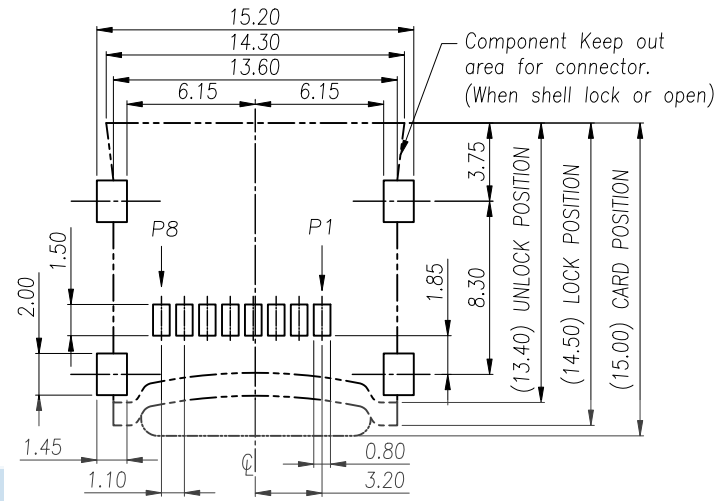
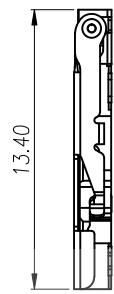
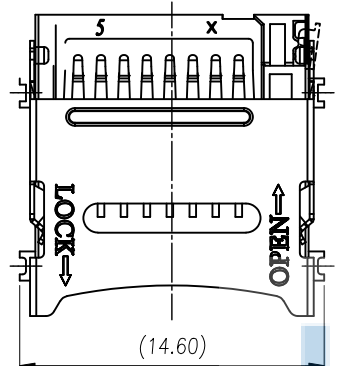
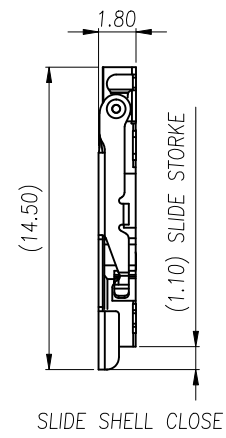
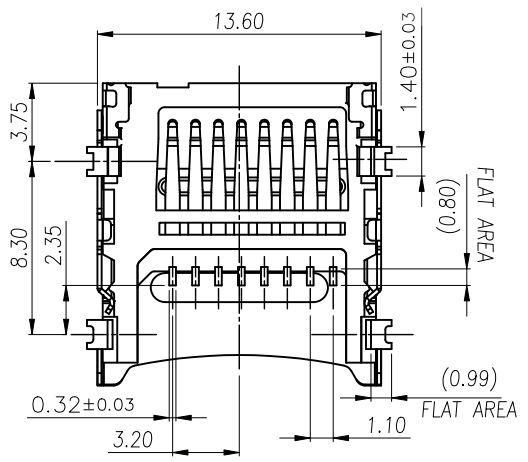
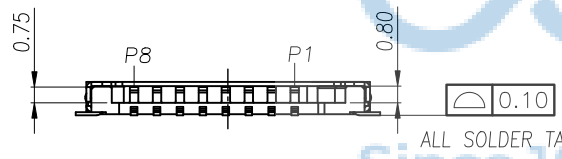


REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF



- Specifications:**
- 1.Material:**
- 1.1.Housing: Thermoplastic,UL94V-0
 - 1.2.Contact: Copper Alloy Gold Plated in contact area plated Sn on solder tails Plated Ni under all,
 - 1.3.Shell:SUS
- 2.Electrical:**
- 3.1.Current Rating: 0.5A
 - 3.3.Contact Resistance: 100mΩ max
 - 3.4.Dielectric Withstanding Voltage: 100V AC
 - 3.5.Insulation Resistance:100MΩ MIN
- 3.Environment characteristics:**
- 1.Operating Temperature:-20°C~+85°C

RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES:±0.05



Memory Card Pin Assianment			
Pin No.	NAME	TYPE	DESCRIPTION
1	DAT 2	I/O/PP	Date Line(bit2)
2	CD/DAT 3	I/O/PP	Card Detect/Date Line(bit3)
3	CMD	PP	Command Response
4	VDD	S	Supply Voltage
5	CLK	I	Colck
6	VSS	S	Supply Voltage Ground
7	DAT0	I/O/PP	Date Line(bit0)
8	DAT1	I/O/PP	Date Line(bit1)

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PDWG.NO: 0361-1

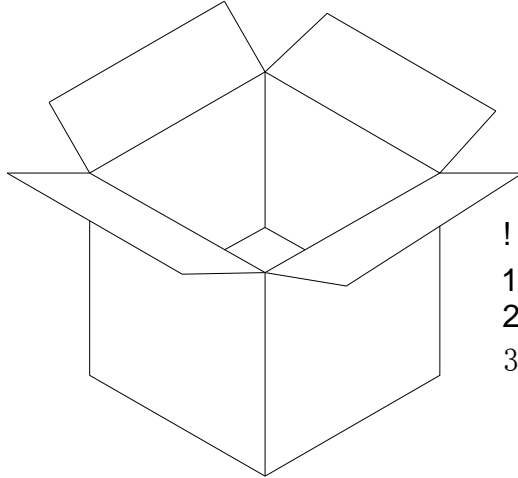
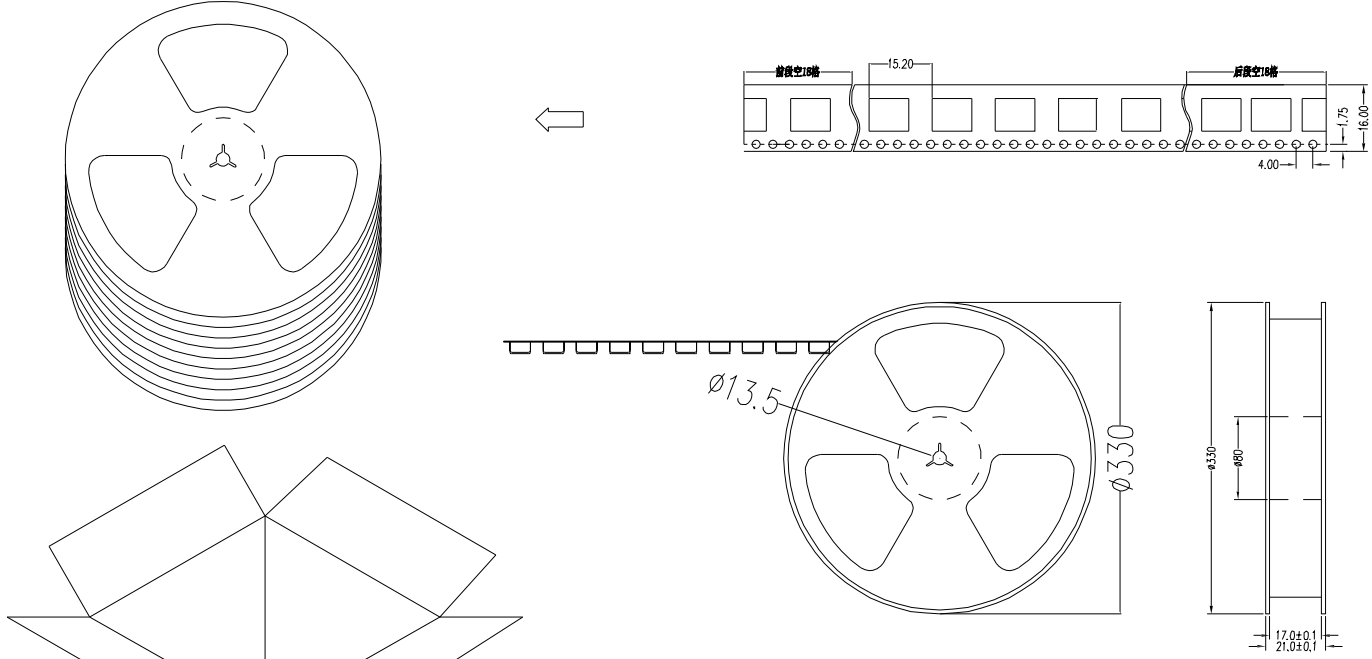
APPD. JM_Zheng
CHKD. LYX
DR. SGF

深圳市步步精科技有限公司

NAME: 2"xù MICRO SD CARD ĩÆ,Ç H=1.8

PJ. NO.: CD.03.02-11-0001
SIZE: A4 DRW NO.:
FINISH: SEE NOTES MAT'L.: SEE NOTES
SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/2

REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF



! " #
 1. \$ % & ' #1200/PCS/卷, 10卷/箱或15卷/) +
 2. \$ %, - . # / G 0 1 2 3 10-20个空格, 中间包装。
 3. 材质:
 载体: 聚丙烯 (PS), 阻抗 $10^{6-9} \Omega$
 DE # < F > ? PET@, 阻抗 $10^{6-11} \Omega$
 卷盘: 聚苯乙烯。
 纸箱规格: 345*345*23MM
 纸箱规格: 345*345*35MM

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PDWG.NO:		DR.	SGF	NAME:	
		APPD.	JM_Zheng	PJ. NO.:	
		CHKD.	LYX	SIZE: A4 DRW NO.:	
				FINISH: SEE NOTES MAT'L.: SEE NOTES	
				SCALE: N/A	REV.: A0
				UNIT: mm	PAGE: 2/2